

Freeform Search

Database:

- US Pre-Grant Publication Full-Text Database
- US Patents Full-Text Database
- US OCR Full-Text Database
- EPO Abstracts Database
- JPO Abstracts Database
- Derwent World Patents Index
- IBM Technical Disclosure Bulletins

Term:

Display: **Documents in Display Format:** **Starting with Number**

Generate: **Hit List** **Hit Count** **Side by Side** **Image**

Search History

DATE: Thursday, January 19, 2006 [Printable Copy](#) [Create Case](#)

<u>Set</u>	<u>Hit</u>	<u>Set</u>
<u>Name</u>	<u>Count</u>	<u>Name</u>
side by side		result set
<i>DB=PGPB,USPT,USOC,EPAB,JPAB,DWPI,TDBD; PLUR=YES; OP=ADJ</i>		
<u>L9</u> l6 and silicon ingot	1	<u>L9</u>
<u>L8</u> L5 and silicon ingot	17	<u>L8</u>
<u>L7</u> l5 and abrasive same amine same (hydroxide or koh or naoh) and ph	122	<u>L7</u>
<u>L6</u> l5 and abrasive same amine(hydroxide or koh or naoh) and ph	122	<u>L6</u>
<u>L5</u> (cutting or lapping or polishing or slicing) and abrasive and amine and (hydroxide or koh or naoh) and ph	2203	<u>L5</u>
<u>L4</u> l3 and ph	2	<u>L4</u>
<u>L3</u> L2 and (hydroxide or koh or naoh or base or basic)	4	<u>L3</u>
<u>L2</u> L1 and amine	4	<u>L2</u>
<u>L1</u> silicon ingot same cutting same slurry	48	<u>L1</u>

END OF SEARCH HISTORY